

PSE Technology Corporation

SPECIFICATION FOR APPROVAL

CUSTOMER	
NOMINAL FREQUENCY	32.768 KHz
HOLDER TYPE	TYPE G3 Cylinder SMD Quartz Crystal
SPEC. NO. (P/N)	G33270007
CUSTOMER P/N	
ISSUE DATE	Apr.25,2011
VERSION	D

APPROVED	PREPARED	QA
Brenda	Clane	Canthur
APPROVED BY CUSTOMER:		AVL Status
Please return one copy with approval to PSE-TW		

PSE Technology Corporation

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http://www.saronix-ecera.com.tw

- *RoHS Exception
- *HF-Halogen Free
- *REACH Compliant



*** A company of PERICOM Semiconductor Corporation ***

G33270007

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VERSION HISTORY

Version No.	Version Date	Customer Receipt Date	Supplier Receipt Date	Description	Notes
А	Mar.12,2010			Initial Release	
В	Jul.23,2010			Changed Pb- Free to RoHS Compliant by Exemption	
С	Aug.26,2010			Correct Marking from 32.768 to 32768	
D	Apr.25,2011			Revised format	



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ELECTRICAL SPECIFICATIONS

SRe Part Number: G33270007

Parameters	Symbol	Specifications	Units	Notes
Nominal Frequency	Fn	32.768	KHz	
Mode of Oscillation	МО	Fundamental		+2° X-Cut
Load Capacitance	CL	12.5	pF	Typical
Calibration Tolerance		± 20	ppm	at 25℃ ± 5℃
Operating Temperature Range	TR	-40~85	°C	
Drive Level	DL	1	μ W	Max.
Series Resonant Resistance	CI/RR	50	ΚΩ	Max.
Temperature Coefficient	K	-0.035	ppm/°C ²	Typical
Aging		± 3	ppm	Max 1st year
Insulation Resistance		500	ΜΩ	at DC 100V ± 15V

Reliability (Mechanical and Environmental Endurance)

No.	Test Items	Test Method and Condition	Requirements
1	Vibration	(1) Vibration Frequency: 10 to 55Hz	Frequency Change: ±10ppm Max.
		(2) Vibration Amplitude: 1.5mm	Resistance Change: ±15% or 5kΩ Max.
		(3) Cycle Time: 1-2min(10-55-10Hz)	
		(4) Direction: X.Y.Z	
		(5) Duration: 2h/each direction	
2	Shock	3 Times free drop from 75cm height to hard wooden	Frequency Change: ±10ppm Max.
		board of thickness more than 30mm	Resistance Change: ±15% or 5kΩ Max.
3	Hermetic seal	Checked:before the molded crystal uints	less than 1 × 10 EXP(-7) mbar.l/sec.
4	High temperature	240 hours at +85°ℂ±2°ℂ	Frequency Change:±10ppm Max.
		After 1-2hours past at room temperature from following	Resistance Change:±25% or 10kohm Max.
		test.	



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5	Low temperature	240 hours at -40℃±2℃	Frequency Change:±10ppm Max.
		After 1-2hours past at room temperature from following	Resistance Change:±15% or 5kohm Max.
		test.	
6	Humidity	240 hours at +85°C ±2°C ,relative humidity 90-95%	Frequency Change:±10ppm Max.
		After 1-2hours past at room temperature from following	Resistance Change:±25% or 10kohm Max
		test.	
7	Temperature cycle	After supplying the following temperature cycle	Frequency Change:±10ppm Max.
		(50cycles)	Resistance Change:±25% or 10kohm Ma:
		+100deg.C 30min 1 to 2min -40deg.C 30min 1 CYCLE	
8	Solderability	Dip the leads of crystal units into the solution (7-10%)	The dipped surface of the leads should b
		of rosin 3±0.5s,then dip it into the tank 5-10s.	at least 95% covered withcontinuous new
		Temperature of solder melted tank is 245°C±5°C	solder coating
9	Reflow soldering	The REFLOW SOLDERING PROFILE of Fig.1 for	After 24h past from frequency test,
		TMXLi-206F families.	Frequency Change:±10ppm Max.
		REFLOW SOLDERING PROFILE	Resistance Change:±25% or 10kohm Ma:
			Notice:
		260°C peak.	Notice: 1 · Using the infrared lamp at soldering
		260°C peak. 250±10°C 250 to 170±10°C 220°C	1 · Using the infrared lamp at soldering
		260°C peak. 250±10°C 250 to 170±10°C 220°C	1 · Using the infrared lamp at soldering process may cause uneven temperature
		260°C peak. 250±10°C 250 to 170±10°C 220°C	Using the infrared lamp at soldering process may cause uneven temperature rise on plastic surface of the parts,so that
		250°C peak. 250±10°C 250 200 170±10°C 220°C 50±10sec	1 \ Using the infrared lamp at soldering process may cause uneven temperature rise on plastic surface of the parts, so that please keep the package temperature



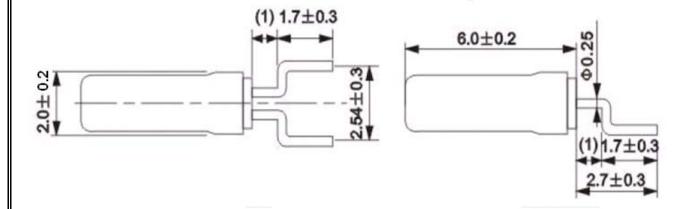
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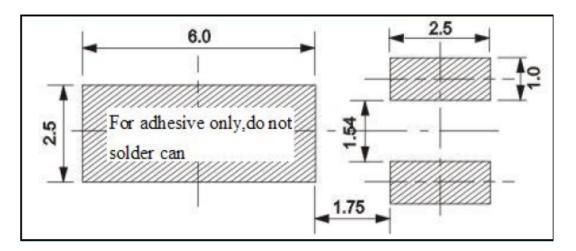
MARKING

32768

DIMENSIONS (Unit:mm)



SOLDER PATTERN



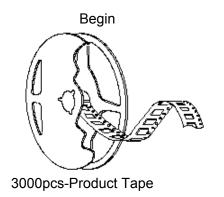
G33270007 VER. D 25-Apr-11 **Packing** Ш 0.3 ≥ B0 ΚQ 0.7±0.1 Α0 2.1 P0 D0ΚO BO Α0 1.5+0.15 9.7 +0.10 1.75 +0.10 7.5 -0.10 2 +0.15 +0,30 +0.10 +0.10 +0.10 +0.10 4.0____ +0.10 16 _0.30 -0.10 -0.10 -0.10 -0.10 -0.10 -0.00 W2 (6) ps W1 W2+0.4 D±0.3 W1±0.2 A±0.5 C±0.2 330 25 100 20 16

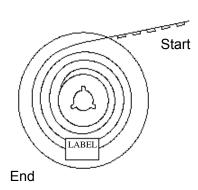


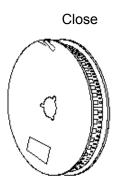
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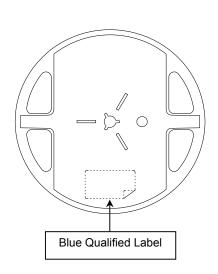
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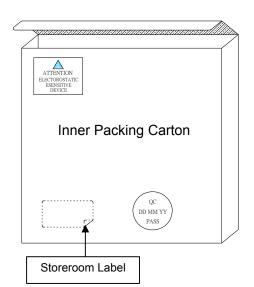
Packing

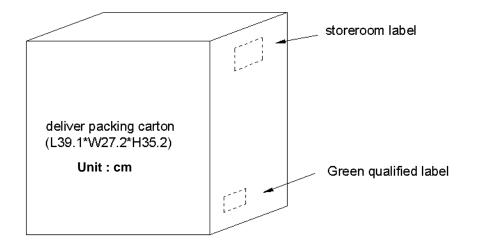














单击下面可查看定价,库存,交付和生命周期等信息

>>Diodes Incorporated(达迩科技(美台))